

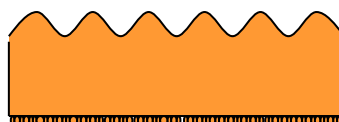
3EC-M2S-VLP

- 極低粗糙度銅箔，適用於細線路蝕刻之減成法製程。
Low profile copper foil, suitable for fine etching in the subtractive process.
- 高抗張力，於薄銅箔易於操作。
High tensile strength, easy to handle thin foil.
- 最薄之 $7\mu\text{m}$ 銅箔具量產能力。
From $7\mu\text{m}$, we line up.

用途/Application

- IC封裝載板
/Semiconductor Package

構成/Composition



生產地點/Production Site

- 日本 / Japan

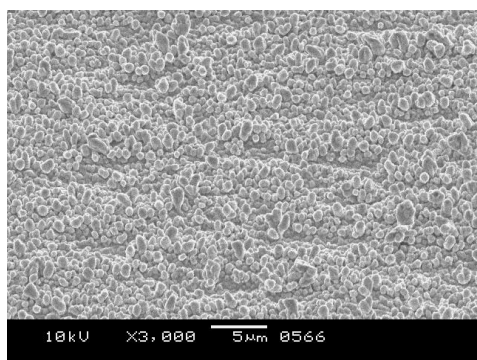
參考特性值/Representative data

	μm	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ^{@FR-4}
3EC-M2S-VLP	9	1.8	500	4	0.6
	12	1.8	500	5	0.7
	18	1.8	500	8	0.8

※上述表列為代表性數據非保證值。

This is representative data, not guarantee.

處理面/Laminate side



阻劑面/ resist side

